# mail

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



# Contact us

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- AVAILABLE IN JAN, JANTX AND JANTXV PER MIL-PRF-19500/118
- GENERAL PURPOSE SILICON DIODES
- METALLURGICALLY BONDED

## **MAXIMUM RATINGS**

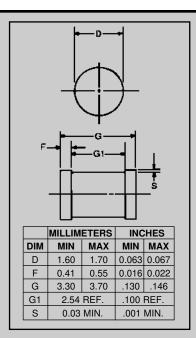
Operating Temperature: -65°C to +175°C Storage Temperature: -65°C to +175°C Operating Current: 200 mA Derating: 1.2mA/°C from 25°C to 150°C 1.0mA/°C from 150°C to 175°C Forward Current: 650mA

### ELECTRICAL CHARACTERISTICS @ 25°C, unless otherwise specified

TYPE	V <sub>RM</sub>	V <sub>RWM</sub>	۱ <sub>0</sub>	<sup>I</sup> о Т <sub>А</sub> =+150°С	<sup>I</sup> FSM T <sub>P</sub> =1/120 S T <sub>A</sub> =25ºC
	V <sub>(pk)</sub>	V <sub>(pk)</sub>	mA	mA	Α
CDLL, 1N5194UR CDLL, 1N5195UR CDLL, 1N5196UR	80 180 250	70 180 225	200 200 200	50 50 50	2 2 2

ТҮРЕ	VF @100mA V dc	I <sub>R1</sub> at V <sub>RWM</sub> nA dc	I <sub>R2</sub> at V <sub>RM</sub> T <sub>A</sub> =25°C μΑ	I <sub>R3</sub> at V <sub>RWM</sub> T <sub>A</sub> = 150°C μA dc
CDLL, 1N5194UR	0.8 - 1.0	25	100	5
CDLL, 1N5195UR	0.8 - 1.0	25	100	5
CDLL, 1N5196UR	0.8 - 1.0	25	100	5

1N5194UR 1N5195UR 1N5196UR CDLL5194 CDLL5195 CDLL5196



# FIGURE 1

### DESIGN DATA

**CASE:** DO-213AA, Hermetically sealed glass case. (MELF, SOD-80, LL34)

LEAD FINISH: Tin / Lead

**THERMAL RESISTANCE:** (R<sub>QJEC</sub>): 100 °C/W maximum

**THERMAL IMPEDANCE: (**Z<sub>QJX</sub>): 70 °C/W maximum

POLARITY: Cathode end is banded.

MOUNTING POSITION: Any.

#### MOUNTING SURFACE SELECTION:

The Axial Coefficient of Expansion (COE) Of this Device is Approximately +6PPM/°C. The COE of the Mounting Surface System Should Be Selected To Provide A Suitable Match With This Device.



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# IN5194UR thru IN5196UR, CDLL5194 thru CDLL5196

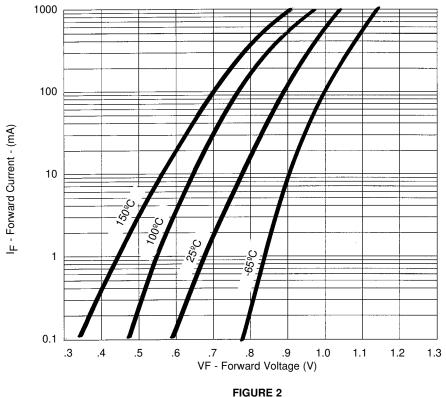
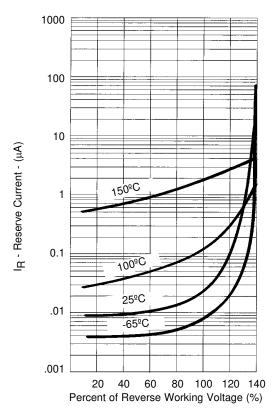


FIGURE 2 Typical Forward Current vs Forward Voltage



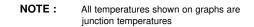


FIGURE 3 Typical Reverse Current vs Reverse Voltage